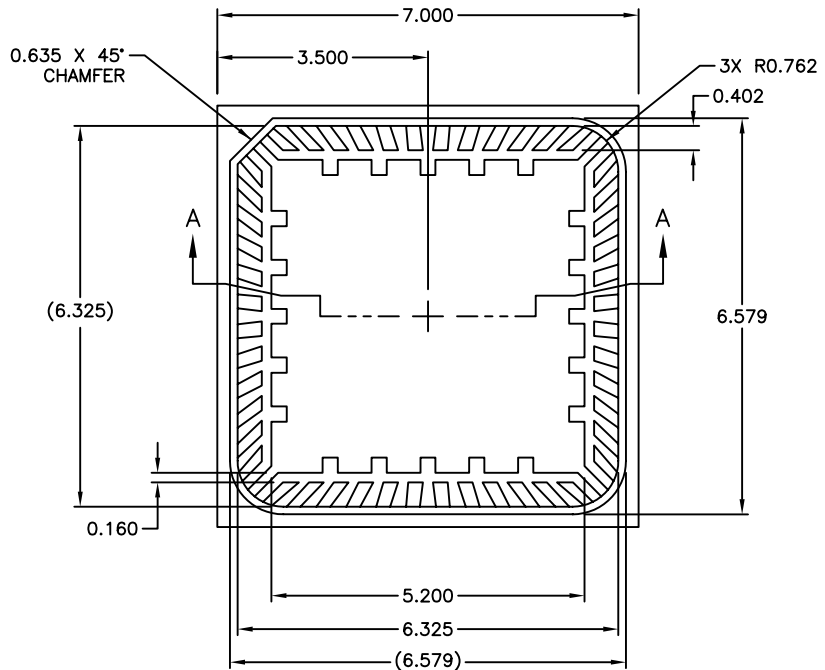
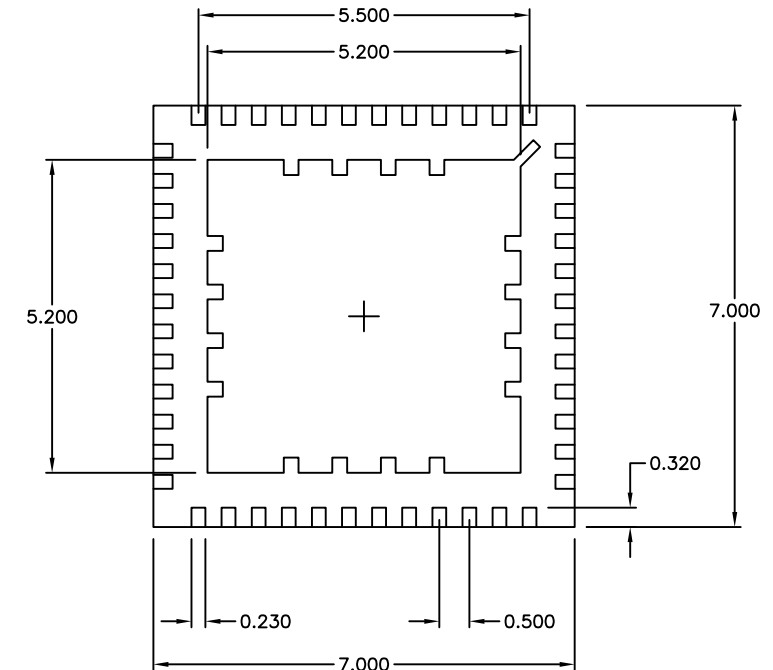
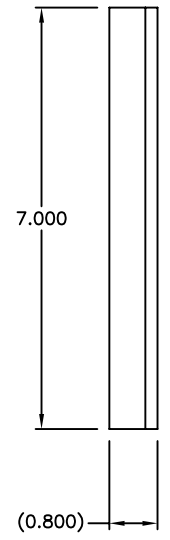


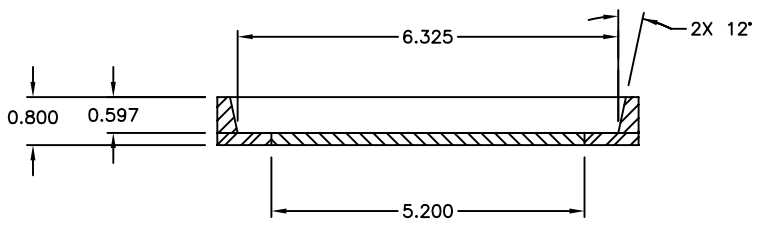
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10501	10/27/05	PRODUCTION RELEASE	D.BENANDO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
- BODY: PLASTIC, SEMICONDUCTOR GRADE.
  - LEAD FRAME: COPPER, FH 194.
  - LEAD FINISH: FULL GOLD PLATE.
  - FRAME THICKNESS: 0.2030 ± 0.0076.
  - DIE PAD: 5.200 X 5.200.
  - JEDEC OUTLINE: MO-220 (VKKD).

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:

X.XX ± 0.15 X.XXXX ± ---  
 X.XXX ± 0.100 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	10/26/05
APP BY	P. FLASKERUD	DATE	10/26/05
CUSTOMER	---		
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48 Lead 7mm x 7mm  
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP7X7-48-OP-02	2
SCALE	CAD FILE	SHEET
NONE	MLP7X7-48-OP-02-R2.DWG	1 OF 1